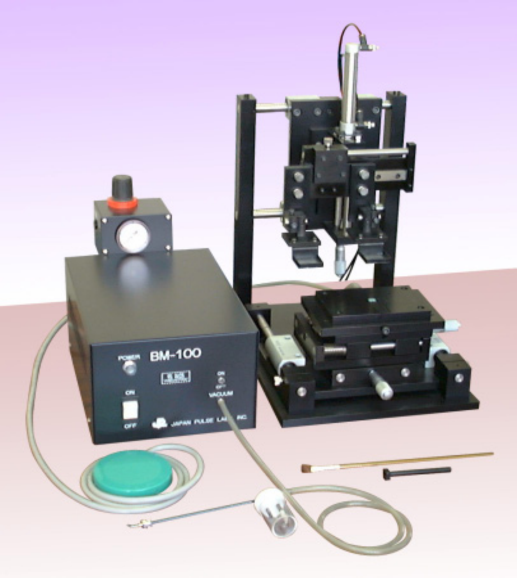
Meeting the needs of the SMT Age



BGA
CSP
MCM

(Micro Screen is option)

Simple Ball Mounting Device BM-100

The BM-100 with MICRO SCREEN (µS-100 series, option) is a machine for mounting ball terminals on BGA, CSP, MCM and other packages. Its applicability ranges from CSP with 48 pins to MCM with 1,500 pins for balls with a diameter of 0.4mmØ to 0.89mmØ. With the machine it is easy to mount ball terminals on a small quantity of packages when re-balling on reprocessed packages, or when mounting balls on chips which are under development etc.

Features

* Application range from CSP with 48 pins to BGA and MCM with 1,500 pins for balls with a diameter of 0.4mmØ to 0.89mmØ. (MICRO SCREEN is optional)
* Flux/cream solder printing and ball aligning are possible with this single machine. (The screen for cream printing and the screen for ball aligning has to be arranged for by the user.)
* The screen position (X, Y, Z) can be fine-adjusted with 10µm accuracy based on the micro meter.
* Fixation of the chip adsorption and the screen vertical movement are controlled automatically with the operating switch.
* It is possible to carry out reflow-soldering immediately after ball alignment; a manual-type N_2 reflow machine RF-110N2 is also available. (Reflow jig for high temperature (290°C) solder ball can be also arranged for.)

Specifications

- µS-100series(option)
  - Size :From 14×28mm to 54×63mm (7 types)
  - Thickness :0.15mm (CSP 0.13mm)
  - Material :Frame SPCC
    Screen SUS304
- Fine-adjustment of X, Y, Z :15mm (10µm steps)
- Dimensions/Mass
  Main unit (W)240×(D)225×(H)410mm 10kg
  Control box (W)180×(D)250×(H)110mm 3kg
- Air input :2 to 5kgf/cm^2
- Hose :OD6mmØ×ID4mmØ

Applicable package

- Size :From 6×6 to 50×50mm
- Number of pins :From 48 to 1,500 pins
- Pitch :1.5mm to 0.5mm
- Ball diameter :0.89mmØ to 0.4mmØ
- Soldering ball :183°C, 290°C

Options

• Micro Screen	µS-100series
• Manual reflow soldering equipment	RF-110 RF-110N2
• Chip adsorption Stage	Special order

Also please refer to the µS-100series Catalogue.

* Specifications subject to change without notice.

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